

## Electronic Patent Application Fee Transmittal

<b>Electronic Patent Application Fee Transmittal</b>				
<b>Application Number:</b>	10790723			
<b>Filing Date:</b>	03-Mar-2004			
<b>Title of Invention:</b>	Wafer level package for micro device and manufacturing method thereof			
<b>First Named Inventor:</b>	Joo Ho Lee			
<b>Filer:</b>	Benjamin J. Hauptman/Ayesha Wilson			
<b>Attorney Docket Number:</b>	2336-247			
Filed as Large Entity				
<b>Utility Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
Independent claims in excess of 3	1201	1	200	200
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>200</b>